
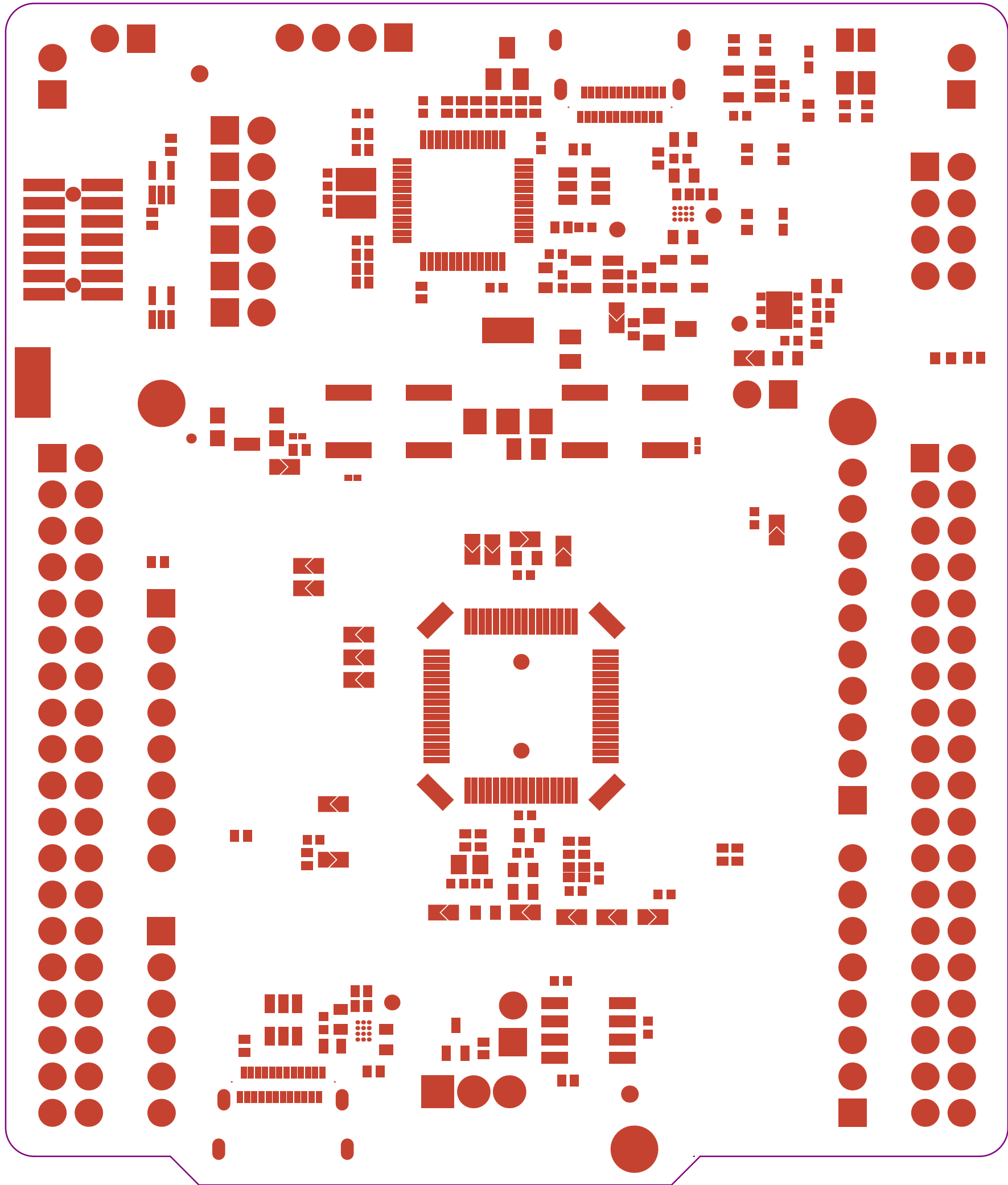

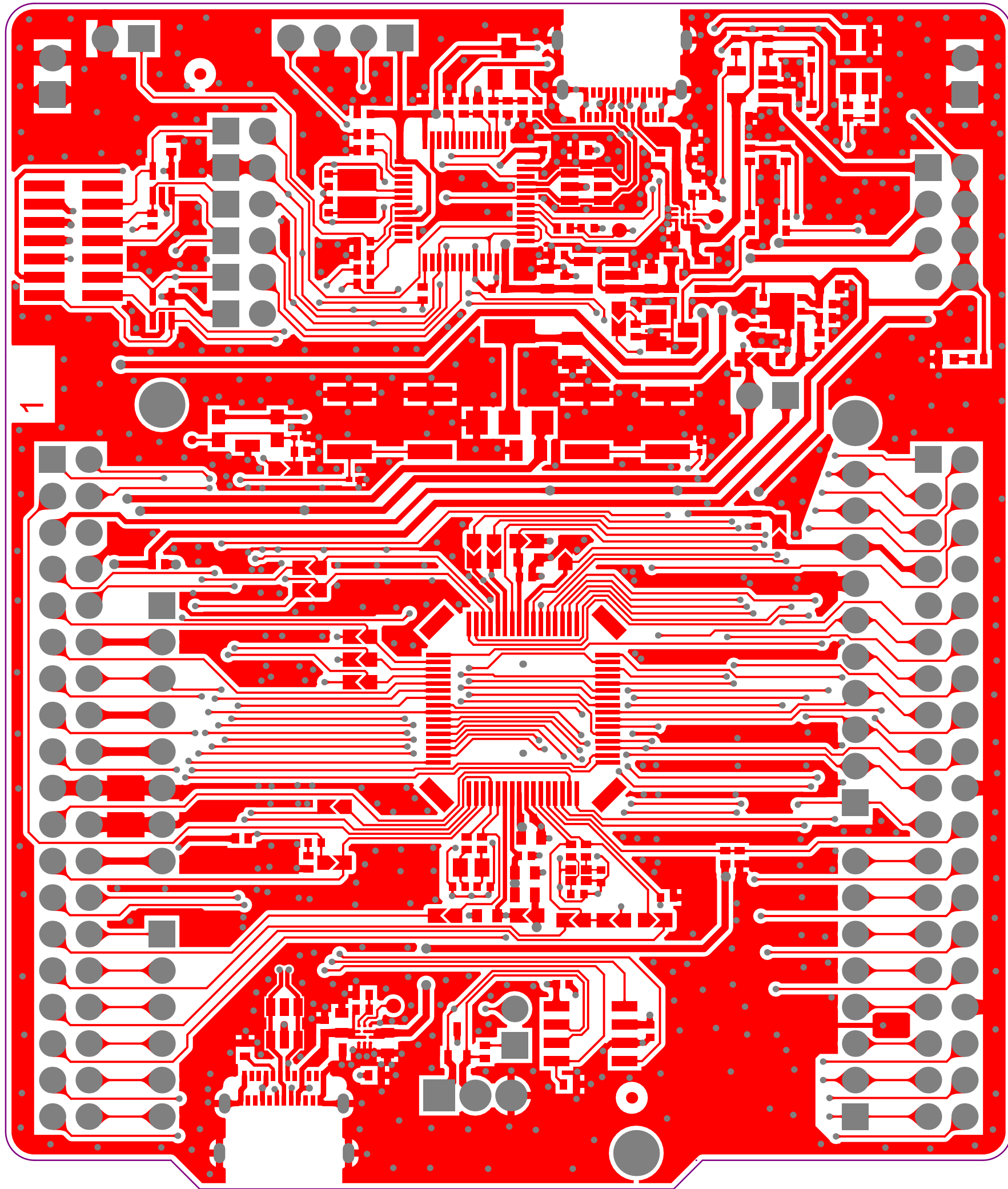



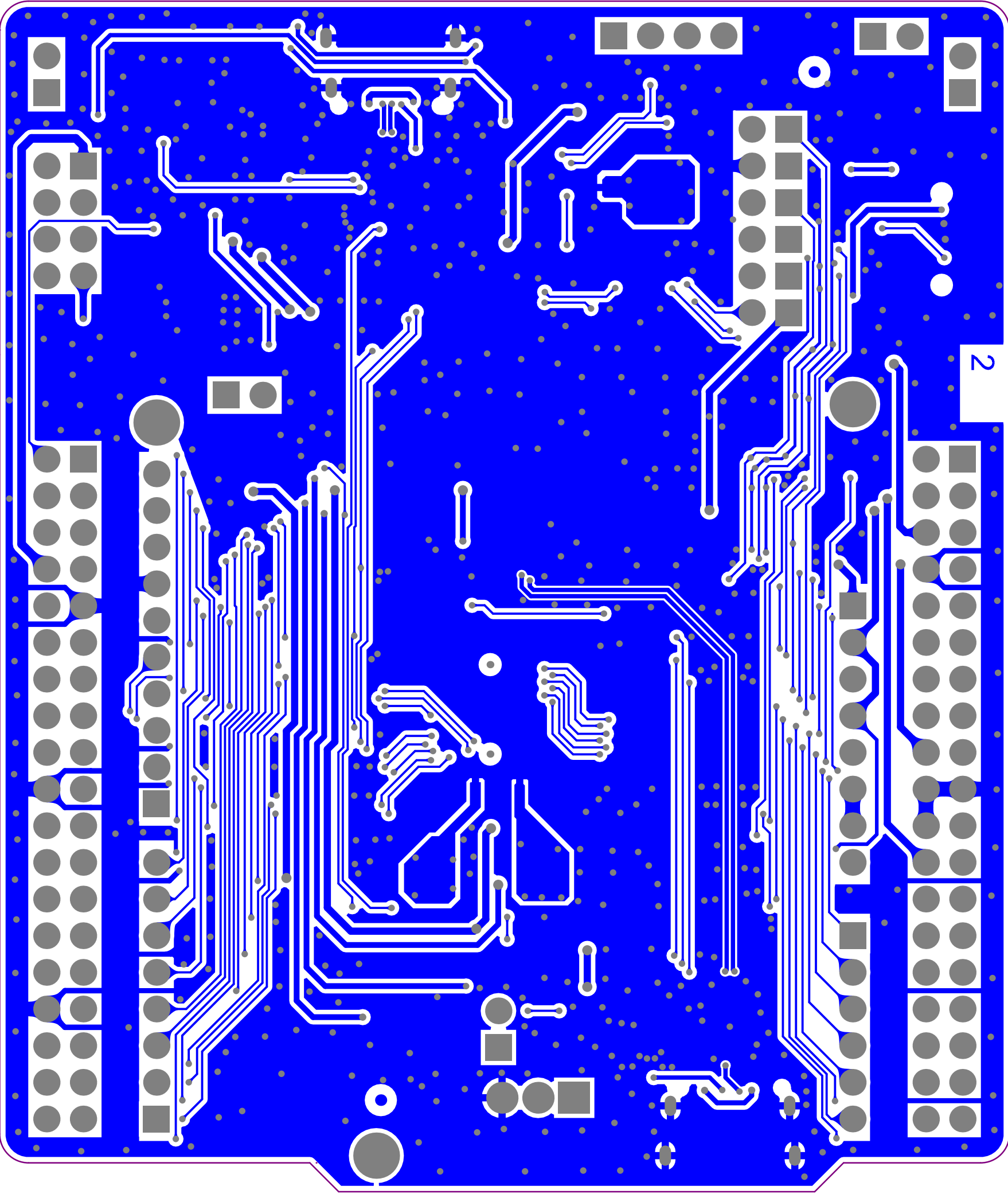
Project: NUCLEO		
Layer: Top Overlay	Gerber: .GTO	
Variant: C071RB	MB2046	
Date: 27-MAR-2024	Rev: B	




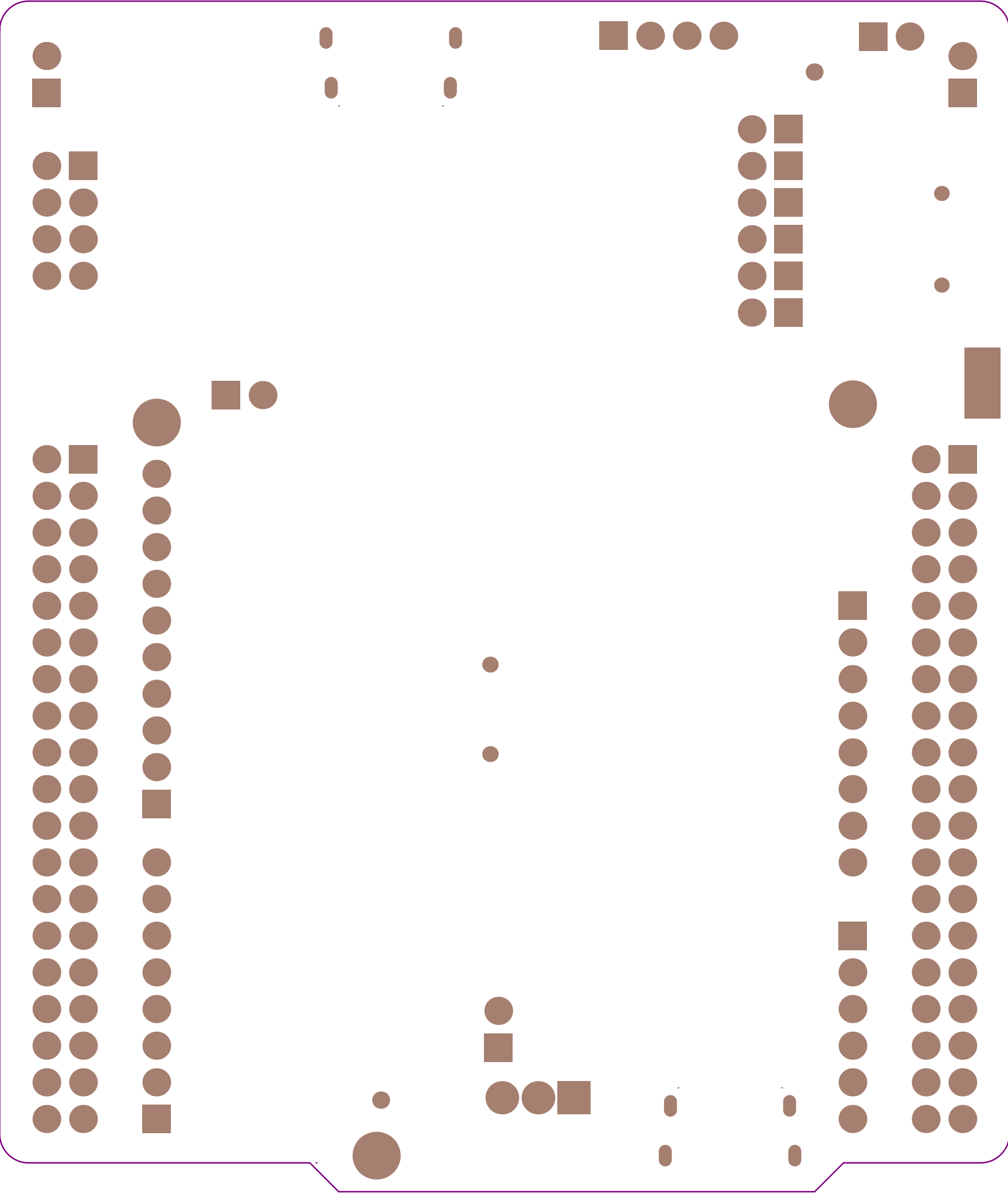
Project: NUCLEO		
Layer: Top Solder	Gerber: .GTS	
Variant: C071RB	MB2046	
Date: 27-MAR-2024	Rev: B	




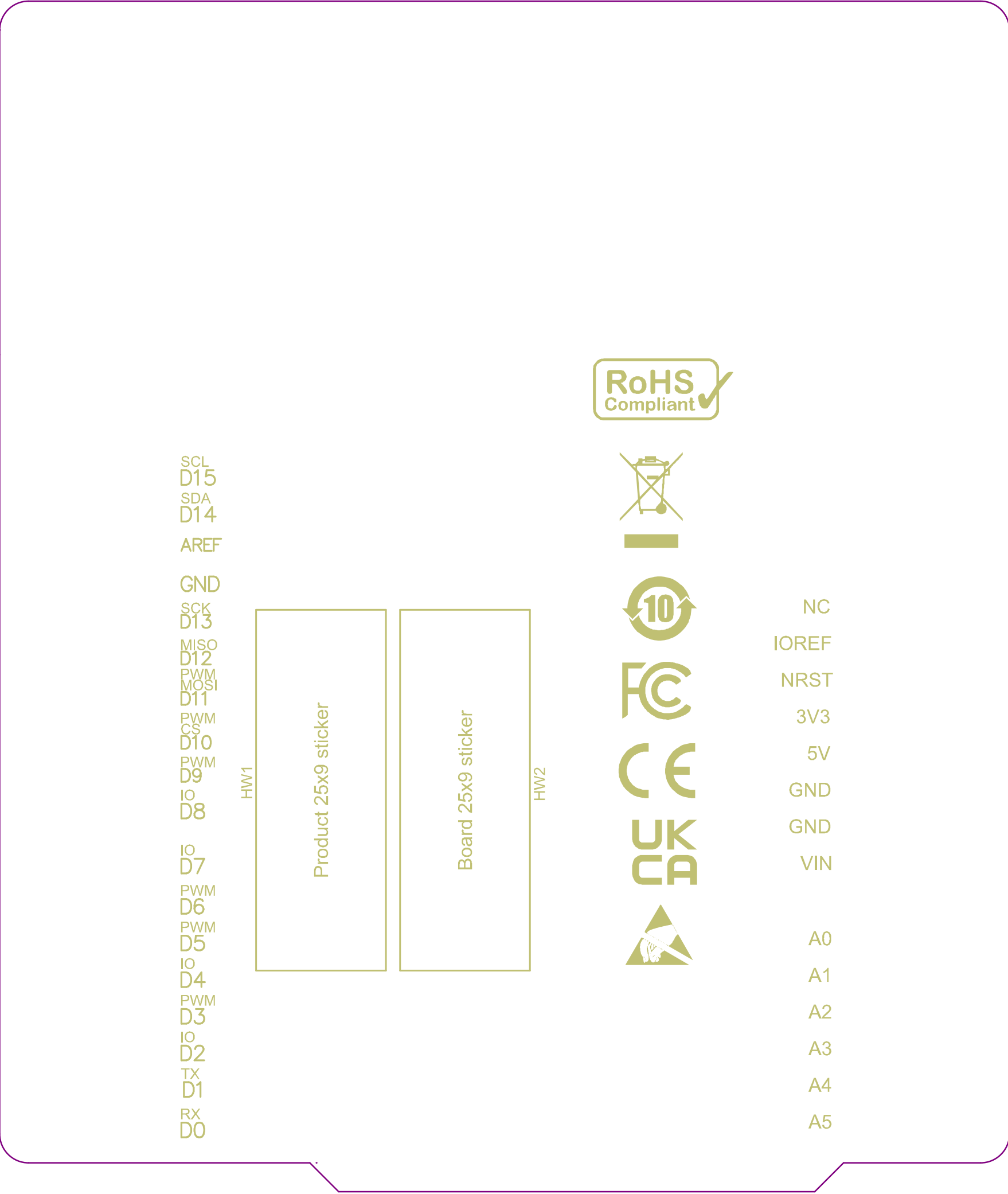
Project: NUCLEO		
Layer: Top Layer	Gerber: .GTL	
Variant: C071RB	MB2046	
Date: 27-MAR-2024	Rev: B	




Project: NUCLEO		
Layer: Bottom Layer	Gerber: .GBL	
Variant: C071RB	MB2046	
Date: 27-MAR-2024	Rev: B	



Project: NUCLEO		
Layer: Bottom Solder	Gerber: .GBS	
Variant: C071RB	MB2046	
Date: 27-MAR-2024	Rev: B	



Project: NUCLEO		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: C071RB	MB2046	
Date: 27-MAR-2024	Rev: B	

« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

☐ IMPEDANCE CONTROL :

G. THROUGH VIA :

☐ STACK-UP :

FR-4

N/A

☐ GREEN

☐ WHITE

☒ ENIG

☐ HASL

☐ NO

☐ TG-170

☒ TG-150

☐ TG-140

☒ WHITE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☐ RED

☐ BLACK

☒ Blue ink PANTONE 2955

☐ IMMERSION TIN

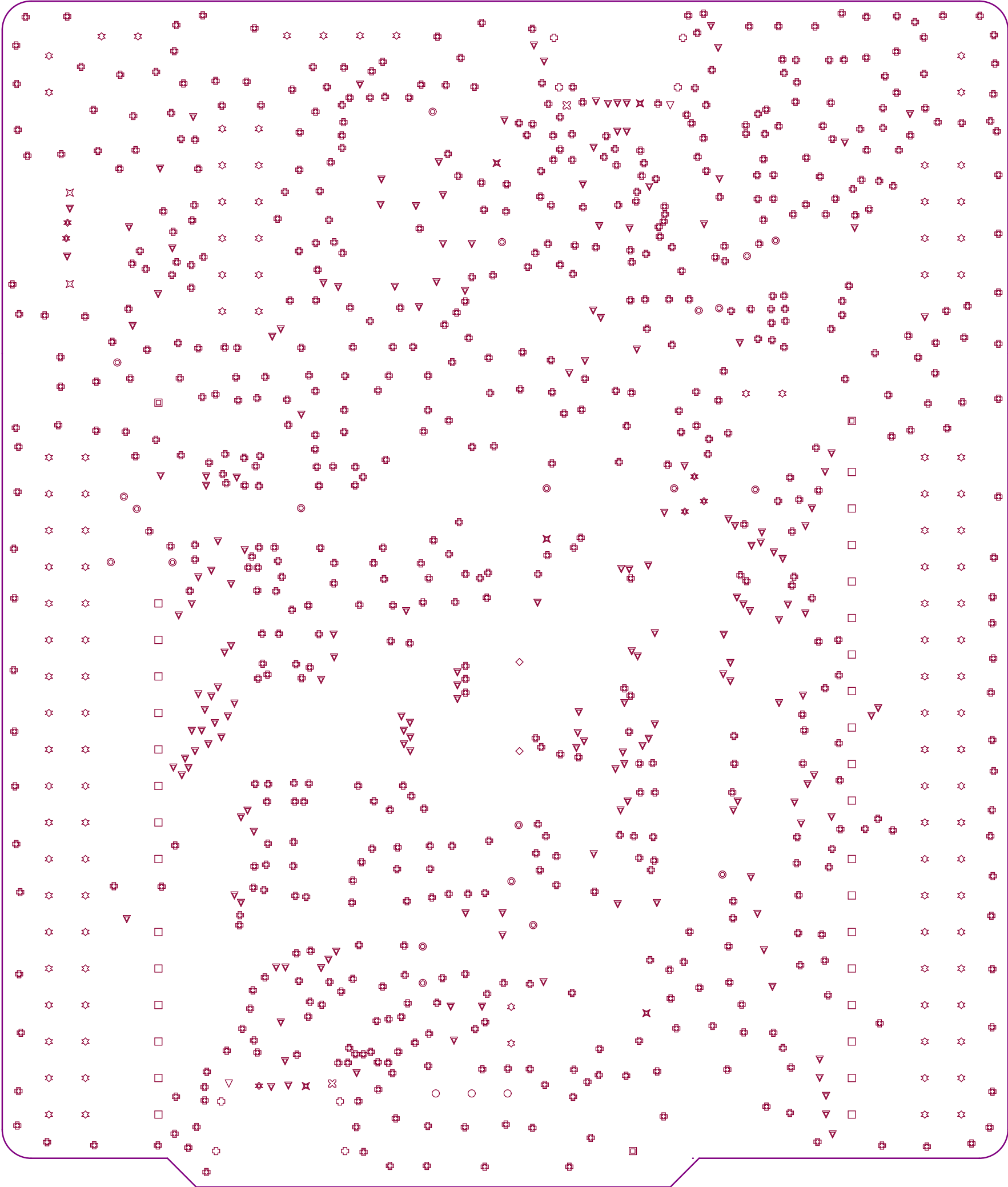
☐ GOLDEN FINGER

☐ NON-CONDUCTIVE EPOXY.

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK

**Plating type :
lead Gold

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer		0.035mm		
	Dielectric 1		1.400mm	4.2	
2	Bottom Layer		0.035mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				



PCB : TYPE 3

ASPECT-RATIO, AXE Z :

6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT

TRACKS : 0.1mm
GAPS : 0.1mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Hole Length	Routed Path Length
▽	2	0.65mm (25.59mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn65m5	-	-
⊗	2	0.65mm (25.59mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn65_95m5	0.95mm (37.40mil)	0.30mm (11.81mil)
✕	2	0.97mm (38.19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn97m101	-	-
◇	2	1.00mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c50hn100m105	-	-
○	3	1.40mm (55.12mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	-	-
▣	3	3.20mm (125.98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c320hn320	-	-
✕	5	0.30mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v50h30m0mx0	-	-
✱	6	0.30mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v50h30m0mx0(Tol0)	-	-
⊕	8	0.50mm (19.69mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	1.10mm (43.31mil)	0.60mm (23.62mil)
◎	21	0.40mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v70h40m0mx0(Tol0)	-	-
□	32	1.10mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	-	-
✱	110	1.00mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	-	-
▽	184	0.25mm (9.84mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v45h25m0mx0	-	-
⊕	646	0.25mm (9.84mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v45h25m0mx0(Tol0)	-	-
	1026 Total									

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

IMPEDANCE TABLE USB HS STLINK					
LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	0.3	0.134	n/a	90 ohm	+/- 15%

Project: NUCLEO

Layer: Drill Drawing

Variant: C071RB

Date: 27-MAR-2024

Gerber: .DRL

MB2046

Rev: B

